

TGF20S

Leader Tech's TGF20S series thermal gap filler is a thermal conductive interface material with natural surface viscosity. The product has low thermal resistance, good flexibility and electrical insulation. The product is of natural stickiness and high compressibility, which can fill the gap well and realize the heat transferred from the heating pad to the heat dissipation part. At the same time, it also plays the role of insulation and damping, which can meet the design requirements of miniaturization and ultra-thin equipment.

Features:

- Ultra-soft
- Excellent compression rate
- Low thermal impedance
- UL94 V-0 recognized
- Excellent electrical insulation performance and heat resistance
- RoHS and Halogen Compliant

Applications:

- Between chip and heat-dissipation modules
- Optoelectronics industry
- Netcom products
- New energy Battery and Automotive Industry
- Household Appliances
- Wearable Technology

Storage Conditions:

- Store in the darkness
- Storage Temperature: ≤ 30 °C
- Storage Humidity: $\leq 70\%$
- When stacking the parts, the parts should not be higher than 7 layers or more than 1mm

Shelf Life:

- Stored at storage conditions: Two years
- Stored in unqualified storage conditions: 6 months

Properties:

Item	Parameter	Unit	Test Method
Color	Light Blue	-	Visual
Thickness	0.8 ~ 3	mm	ASTM D374
Hardness	20(±5)	Shore 00	ASTM D2240
Density	2.4(±0.5)	g/cc	ASTM D792
Tensile Strength	≥0.15	Mpa	ASTM D412
Elongation	≥70	%	ASTM D412
Compression Ratio	≥50(@50PSI)	%	ASTM D695
UL Certification	V-0, 5V	-	UL94
Operating Temperature	-50 ~ 180	°C	IEC 600068-2-14

Thermal Characteristics:

Thermal Conductivity	2.0(±0.3)	W / m·K	ASTM D5470
Thermal Resistance	≤0.7(@20PSI/1mm)	°Cin ² /W	ASTM D5470

Electrical Properties:

Breakdown Voltage	≥8	KV/mm	ASTM D149
Volume Resistivity	≥10 ¹⁰	Ω·cm	ASTM D257
Dielectric constant	≥2	@1MHz	ASTM D150
Dielectric loss	≤0.1	@1MHz	ASTM D150